Reinforcement of Flip-Chip Die Bonding and Rigid Substrate Connection

Underfills

LOCTITE ECCOBOND FP4547	LOCTITE ECCOBOND FP 5201	LOCTITE ECCOBOND UF 8830

Properties		Units	LOCTITE ECCOBOND FP4547	LOCTITE ECCOBOND FP 5201	LOCTITE ECCOBOND UF 8830
Viscosity (Brookfield CP51 / 5 rpm)		mPa.s	18,000	21,000	12,000
Glass Transition Temperature (T_g)		°C	135	171	92
Modulus @ 25°C		N / mm²	11,000	5,800	5,800
CTE	below	ppm / °C	21	31	31
	above		80	65	120
Recommended Cure			30 min. @ 165°C	30 min. @ 165°C	2 hrs. @ 150°C

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